

	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Ret
1	US 5801441 A	19980901	25	Microelectronic mounting with multiple lead	257/696	257/688; 257/689;	
2	US 6222136 B1	20010424	19	Printed circuit board with continuous connective bumps	174/254	174/255; 174/262;	
3	US 6678952 B2	20040120	22	Method of making a microelectronic package	29/847	174/254; 29/835;	
4	US 5556812 A	19960917	8	Connection and build-up technique for multichip	438/623	216/18; 427/96;	
5	US 5518964 A	19960521	27	Microelectronic mounting with multiple lead	438/113	257/E23.065; 257/E23.067;	
6	US 5436062 A	19950725	24	Process for the production of printed circuit boards	428/209	174/254; 174/266;	
7	US 5173055 A	19921222	12	Area array connector	439/66	439/591; 439/81;	
8	US 6518160 B1	20030211	17	Method of manufacturing connection components using	438/612	216/18; 438/611;	
9	US 6329607 B1	20011211	22	Microelectronic lead structures with dielectric	174/261	228/180.21; 257/688;	
10	US 6200143 B1	20010313	20	Low insertion force connector for	439/70	29/830; 29/879;	
11	US 6194291 B1	20010227	24	Microelectronic assemblies with multiple leads	438/455	257/666; 257/674;	